Product data sheet

1. General description

Silicon Carbide Schottky diode designed for high frequency switched mode power supplies in a TO252 (DPAK) plastic package.

2. Features and benefits

- · Highly stable switching performance
- High forward surge capability I_{FSM}
- · Extremely fast reverse recovery time
- Superior in efficiency to Silicon Diode alternatives
- Reduced losses in associated MOSFET
- Reduced EMI
- Reduced cooling requirements
- RoHS compliant

3. Applications

- Power factor correction
- Telecom/Server SMPS
- UPS
- PV inverter
- PC Silverbox
- LED/OLED TV
- Motor Drives

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V _{RRM}	repetitive peak reverse voltage		-	-	650	V
I _{F(AV)}	average forward current	δ = 0.5 ; T _{mb} ≤ 125 °C; square-wave pulse; Fig. 1; Fig. 2; Fig. 3; Fig. 4	-	-	6	A
Tj	junction temperature		-	-	175	°C
Static charac	teristics					
V _F	forward voltage	I _F = 6 A; T _j = 25 °C; <u>Fig. 6</u>	-	1.5	1.7	V
		I _F = 6 A; T _j = 150 °C; <u>Fig. 6</u>	-	1.8	2.1	V
Dynamic cha	racteristics					
Q _r	recovered charge	$I_F = 6 \text{ A}; dI_F/dt = 500 \text{ A/}\mu\text{s}; V_R = 400 \text{ V};$ $T_j = 25 \text{ °C}; Fig. 7$	-	10	-	nC

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	n.c.	not connected	mb	K — A
2	K	cathode[1]		001aaa020
3	Α	anode		
mb	К	mounting base; connected to cathode	DPAK (TO252NS)	

^[1] It is not possible to connect to pin 2 of the TO252 package.

6. Ordering information

Table 3. Ordering information

Type number	Package						
	Name	Description	Version				
NXPSC06650D	DPAK	plastic single-ended surface-mounted package (DPAK); 3 leads (one lead cropped)	TO252NS				

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{RRM}	repetitive peak reverse voltage		-	650	V
V_{RWM}	crest working reverse voltage		-	650	V
V_R	reverse voltage	DC	-	650	V
I _{F(AV)}	average forward current	δ = 0.5 ; T _{mb} ≤ 125 °C; square-wave pulse; Fig. 1; Fig. 2; Fig. 3; Fig. 4	-	6	Α
I _{FRM}	repetitive peak forward current	δ = 0.5 ; t _p = 25 µs; square-wave pulse	-	12	Α
I _{FSM}	non-repetitive peak	t _p = 10 ms; T _{j(init)} = 25 °C; sine-wave pulse	-	36	Α
	forward current	t_p = 10 μ s; $T_{j(init)}$ = 25 °C; square-wave pulse	-	310	А
T _{stg}	storage temperature		-55	175	°C
T _j	junction temperature		-	175	°C

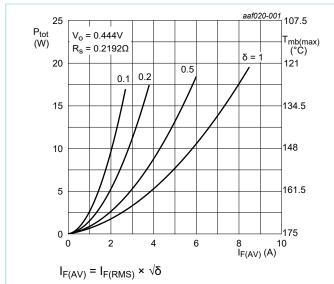


Fig. 1. Forward power dissipation as a function of average forward current; square waveform; maximum values

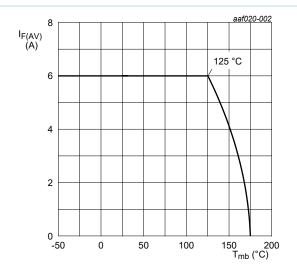


Fig. 2. Forward current as a function of mounting base temperature; maximum values

WeEn Semiconductors NXPSC06650D

Silicon Carbide Diode

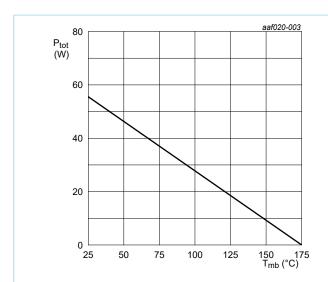


Fig. 3. Total power dissipation as a function of mounting base temperature

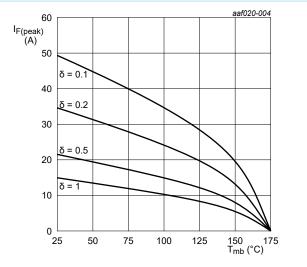


Fig. 4. Current derating as a function of mounting base temperature

8. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
R _{th(j-mb)}	thermal resistance from junction to mounting base	<u>Fig. 5</u>	-	-	2.7	K/W
R _{th(j-a)}	thermal resistance from junction to ambient free air	Device mounted on an FR4 Printed- Circuit Board	-	50	-	K/W

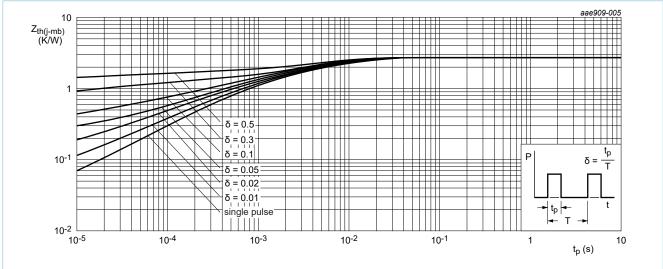
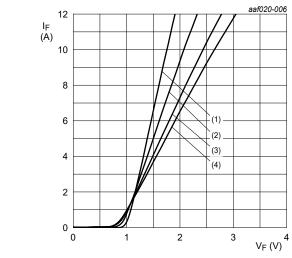


Fig. 5. Transient thermal impedance from junction to mounting base as a function of pulse duration

9. Characteristics

Table 6. Characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static charac	cteristics					,
V _F	forward voltage	I _F = 6 A; T _j = 25 °C; <u>Fig. 6</u>	-	1.5	1.7	V
		I _F = 6 A; T _j = 150 °C; <u>Fig. 6</u>	-	1.8	2.1	V
I _R	reverse current	V _R = 650 V; T _j = 25 °C	_	-	200	μA
		V _R = 650 V; T _j = 150 °C	_	-	640	μA
Dynamic cha	aracteristics					,
Q _r	recovered charge	$I_F = 6 \text{ A}; dI_F/dt = 500 \text{ A/}\mu\text{s}; V_R = 400 \text{ V};$ $T_j = 25 \text{ °C}; Fig. 7$	-	10	-	nC
C _d	diode capacitance	f = 1 MHz; V _R = 1 V; T _j = 25 °C	-	190	-	pF
		$f = 1 \text{ MHz}; V_R = 300 \text{ V}; T_j = 25 ^{\circ}\text{C}$	-	23	-	pF
		f = 1 MHz; V _R = 600 V; T _j = 25 °C	-	19	-	pF



(1) T_j = 25 °C; typical values (2) T_j = 100 °C; typical values (3) T_j = 150 °C; typical values (4) T_j = 175 °C; typical values



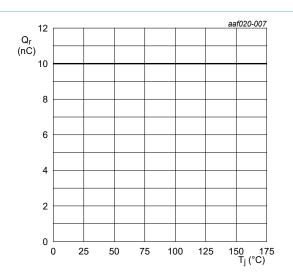


Fig. 7. Recovered charge as a function of junction temperature

10. Package outline

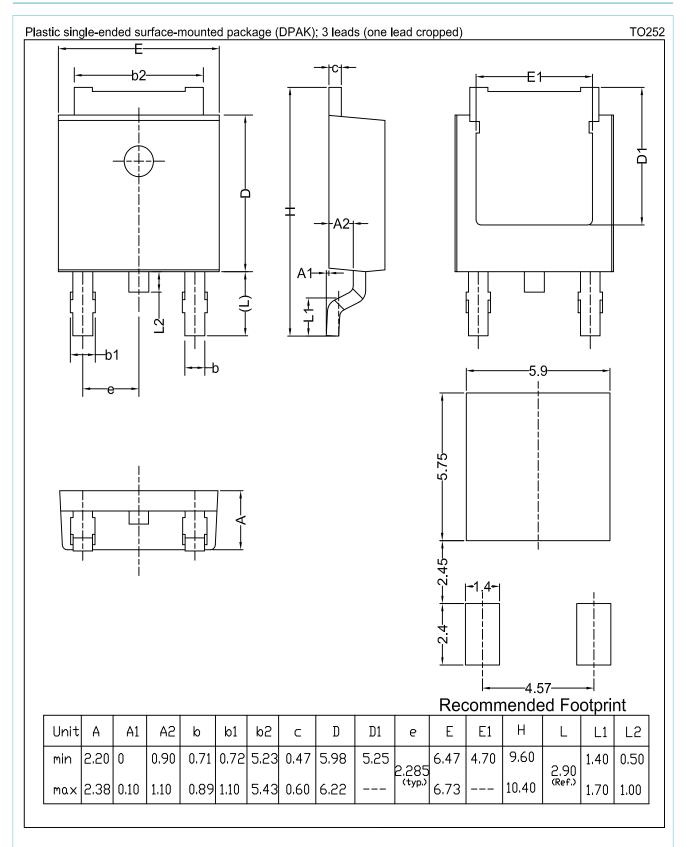


Fig. 8. Package outline DPAK (TO252NS)

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11. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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